



Product Change Notification: MFOL-31SHMS864

Date:

30-Apr-2026

Product Category:

Gate Drivers and Motor Drivers

Notification Subject:

CCB 8110 Initial Notice: Qualification of MTAI as an additional assembly site for selected MIC4426, MIC4420, MIC4423, MIC4429, MIC4425, MIC4427, MIC4424, and MIC4428 device families available in 8L SOIC (3.90mm) package.

Affected CPNs:

[MFOL-31SHMS864_Affected_CPN_04302026.pdf](#)

[MFOL-31SHMS864_Affected_CPN_04302026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for selected MIC4426, MIC4420, MIC4423, MIC4429, MIC4425, MIC4427, MIC4424, and MIC4428 device families available in 8L SOIC (3.90mm) package.

Pre and Post Summary Changes:

	Pre Change		Post Change			Change (Yes/No)
Assembly Site	Stars Microelectronics (Thailand)	Unisem (M) Berhad Perak,	Stars Microelectronics (Thailand)	Unisem (M) Berhad Perak,	Microchip Technology Thailand	Yes

	Public Company Limited (STAR)	Malaysia (UNIS)	Public Company Limited (STAR)	Malaysia (UNIS)	(HQ) (MTAI)	
Wire Material	Au	Au	Au	Au	CuPdAu	Yes
Die Attach Material	2200D (PFAS)	8290 (PFAS free)	2200D (PFAS)	8290 (PFAS free)	CRM-1064L (PFAS free)	Yes
Molding Compound Material	G600	G600KA	G600	G600KA	G634A	Yes
Lead-Frame Material	C194	A194	C194	A194	CDA194	No
Lead-Frame DAP Surface Prep	NiPdAu	NiPdAu	NiPdAu	NiPdAu	Bare Cu	Yes
Lead-Frame Lead Lock	No	No	No	No	Yes	Yes
	See Pre and Post Change Summary attachment for comparison.					Yes
Top Marking	See Pre and Post Change Summary attachment for comparison.					Yes

Note: *C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: May 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	April 2026					May 2026				
Work Week	14	15	16	17	18	19	20	21	22	23
Initial PCN Issue Date		X								
Qual Report Availability							X			
Final PCN Issue Date							X			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: April 08, 2026: Issued initial notification.

April 30, 2026: Re-issued initial notification to update LF DAP Surface Prep from "NiPdAu" to "Bare Cu" in Pre and Post Change Summary Attachment.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MFOL-31SHMS864_Pre and Post Change Summary.pdf](#)

[PCN_MFOL-31SHMS864_Qualification Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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